

L Number	Hits	Search Text	DB	Time stamp
-	8556	low adj dielectric adj constant	USPAT; US-PGPUB	2003/01/07 16:14
-	13702	low adj2 dielectric	USPAT; US-PGPUB	2003/01/07 16:15
-	467203	interconnect\$3	USPAT; US-PGPUB	2003/01/07 16:15
-	26535	metallization	USPAT; US-PGPUB	2003/01/07 16:16
-	5386	(interconnect\$3 or metallization) and ((low adj dielectric adj constant) or (low adj2 dielectric))	USPAT; US-PGPUB	2003/01/07 16:17
-	2571	low adj K	USPAT; US-PGPUB	2003/01/07 16:17
-	4400	(interconnect\$3 or metallization) and ((low adj dielectric adj constant) or (low adj K))	USPAT; US-PGPUB	2003/01/07 16:17
-	60558	438/\$.ccls.	USPAT; US-PGPUB	2003/01/07 16:18
-	79674	257/\$.ccls.	USPAT; US-PGPUB	2003/01/07 16:18
-	3120	((interconnect\$3 or metallization) and ((low adj dielectric adj constant) or (low adj2 dielectric))) or ((interconnect\$3 or metallization) and ((low adj dielectric adj constant) or (low adj K)))) and (438/\$.ccls. or 257/\$.ccls.)	USPAT; US-PGPUB	2003/01/07 16:20
-	729	HSQ	USPAT; US-PGPUB	2003/01/07 16:20
-	808	hydrogen adj silsesquioxane	USPAT; US-PGPUB	2003/01/07 16:20
-	3546	tetraethylorthosilicate	USPAT; US-PGPUB	2003/01/07 16:21
-	115	tetraethyloxysilane	USPAT; US-PGPUB	2003/01/07 16:21
-	11540	TEOS	USPAT; US-PGPUB	2003/01/07 16:22
-	321	(interconnect\$3 or metallization) and (HSQ or (hydrogen adj silsesquioxane)) and (tetraethylorthosilicate or tetraethyloxysilane or TEOS)	USPAT; US-PGPUB	2003/01/07 20:35